

Global Semiconductor Bonding Equipment Market Size study & Forecast, by Type (Permanent Bonding Equipment, Temporary Bonding Equipment, and Hybrid Bonding Equipment), by Application (Advanced Packaging, Power IC & Power Discrete, Photonic Devices, MEMS Sensors & Actuators, Engineered Substrates, and CMOS Image Sensor (CIS)), and Regional Analysis, 2023-2030

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Abstracts

Global Semiconductor Bonding Equipment Market is valued at approximately USD X billion in 2022 and is anticipated to grow with a healthy growth rate of more than 11.76% over the forecast period 2023-2030. Wafer substrate bonding units are used to adhere a thin substrate wafer to a support carrier disc during the wafer bonding process. This is accomplished using a variety of bonding procedures that call for different tools or equipment. Permanent bonding, transient bonding, and hybrid bonding are all forms of equipment. Atoms are bound together to produce a homogenous structure in semiconductor arrangements, which are utilized to create various integrated circuits (ICs) and production equipment. The material's structure is consistent and almost identical throughout the bonding model. The market growth is driven by key factors such as rising demand for Semiconductor Chips across various applications and increasing investment by Semiconductor manufacturers to expand their manufacturing capacity.

According to Statista, the worldwide semiconductor industry generated slightly under 600 billion dollars in sales in 2022, an increase from the previous year when total revenues totaled 595 billion dollars. The semiconductor market's revenues are only projected to be 630.9 billion dollars in 2024. Additionally, in December 2022, China

announced a subsidy program for its semiconductor sector worth more than CNY 1 trillion (USD 143 billion), which considerably increased chip self-sufficiency and was a response to American efforts to hinder its technological advancement. The majority of the financial aid is expected to be utilized to finance Chinese companies' acquisitions of domestic semiconductor equipment, which will likely boost regional market demand. Moreover, adoption of IoT and AI in the automotive sector and technological investments in offering next-generation semiconductor bonding solutions create lucrative opportunities during the years. However, high cost of ownership and increased complexity owing to miniaturization of circuits stifle market growth throughout the forecast period of 2023-2030.

The key regions considered for the Global Semiconductor Bonding Equipment Market study include Asia Pacific, North America, Europe, Latin America, and Middle East & Africa. Asia Pacific is leading the global market share and expected to be the fastest growing region owing to growing investments to support the semiconductor industry and strategic investments by key domestic suppliers.

Major market players included in this report are:

Kulicke and Soffa Industries Inc.

EV Group

ASMPT Semiconductor Solutions

MRSI Systems. (Myronic AB)

WestBond Inc.

Panasonic Industry Co. Ltd.

Palomar Technologies

Dr. Tresky AG

BE Semiconductor Industries NV

Fasford Technology Co.Ltd (Fuji Group)

Recent Developments in the Market:

October 2022, a new semiconductor assembly and testing facility is likely to be built in Penang, according to proposals released by BE Semiconductor Industries NV. The new facility, which consists of two buildings (Plants 4 and 5), will be in the Bayan Lepas Free Industrial Zone and have a total built-up area of 982,000 square feet. The project is anticipated to be finished in 2025 and would open over 2,700 job possibilities in the location.

July 2022, the most recent development in the MRSI-H/HVM-series product line, MRSI-H-HPLD+, has been introduced by MRSI Systems (Mycronic Group). In order to dramatically increase productivity utilising parallel processing while preserving excellent precision and flexibility, this new variation of MRSI-H-HPLD is designed for high-power laser die attachment applications.

Global Semiconductor Bonding Equipment Market Report Scope:

Historical Data – 2020 - 2021

Base Year for Estimation – 2022

Forecast period - 2023-2030

Report Coverage - Revenue forecast, Company Ranking, Competitive Landscape, Growth factors, and Trends

Segments Covered – Type, Application, Region

Regional Scope - North America; Europe; Asia Pacific; Latin America; Middle East & Africa

Customization Scope - Free report customization (equivalent up to 8 analyst's working hours) with purchase. Addition or alteration to country, regional & segment scope*

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values to the coming years. The report is designed to

incorporate both qualitative and quantitative aspects of the industry within countries involved in the study.

The report also caters detailed information about the crucial aspects such as driving factors & challenges which will define the future growth of the market. Additionally, it also incorporates potential opportunities in micro markets for stakeholders to invest along with the detailed analysis of competitive landscape and product offerings of key players. The detailed segments and sub-segment of the market are explained below:

By Type:

Permanent Bonding Equipment

Temporary Bonding Equipment

Hybrid Bonding Equipment

By Application:

Advanced Packaging

Power IC and Power Discrete

Photonic Devices

MEMS Sensors and Actuators

Engineered Substrates

CMOS Image Sensors (CIS)

By Region:

North America

U.S.

Canada

Europe

UK

Germany

France

Spain

Italy

ROE

Asia Pacific

China

India

Japan

Australia

South Korea

RoAPAC

Latin America

Brazil

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Middle East & Africa

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Rest of Middle East & Africa

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